Infineon Technologies - SAK-XC888C-6FFI 5V AC Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	XC800
Core Size	8-Bit
Speed	24MHz
Connectivity	CANbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	48
Program Memory Size	24KB (24K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.75K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	PG-TQFP-64
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/sak-xc888c-6ffi-5v-ac

Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (TQFP-48/64)	Type	Reset State	Function	
P0.4	1/64		Hi-Z	MTSR_1	SSC Master Transmit Output/ Slave Receive Input
				CC62_1	Input/Output of Capture/Compare channel 2
				TXD1_0	UART1 Transmit Data Output/Clock Output
P0.5	2/1		Hi-Z	MRST_1	SSC Master Receive Input/Slave Transmit Output
				EXINT0_0	External Interrupt Input 0
				T2EX1_1	Timer 21 External Trigger Input
				RXD1_0	UART1 Receive Data Input
				COUT62_1	Output of Capture/Compare channel 2
P0.6	–/2		PU	GPIO	
P0.7	47/62		PU	CLKOUT_1	Clock Output

Table 14 CCU6 Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
FB_H	**CCU6_CC60RH** **Reset: 00_H** Capture/Compare Register for Channel CC60 High	Bit Field	CC60VH							
		Type	rh							
FC_H	**CCU6_CC61RL** **Reset: 00_H** Capture/Compare Register for Channel CC61 Low	Bit Field	CC61VL							
		Type	rh							
FD_H	**CCU6_CC61RH** **Reset: 00_H** Capture/Compare Register for Channel CC61 High	Bit Field	CC61VH							
		Type	rh							
FE_H	**CCU6_CC62RL** **Reset: 00_H** Capture/Compare Register for Channel CC62 Low	Bit Field	CC62VL							
		Type	rh							
FF_H	**CCU6_CC62RH** **Reset: 00_H** Capture/Compare Register for Channel CC62 High	Bit Field	CC62VH							
		Type	rh							
RMAP = 0, PAGE 2										
$9A_H$	**CCU6_T12MSELL** **Reset: 00_H** T12 Capture/Compare Mode Select Register Low	Bit Field	MSEL61				MSEL60			
		Type	rw				rw			
$9B_H$	**CCU6_T12MSELH** **Reset: 00_H** T12 Capture/Compare Mode Select Register High	Bit Field	DBYP	HSYNC			MSEL62			
		Type	rw	rw			rw			
$9C_H$	**CCU6_IENL** **Reset: 00_H** Capture/Compare Interrupt Enable Register Low	Bit Field	ENT12PM	ENT12OM	ENCC62F	ENCC62R	ENCC61F	ENCC61R	ENCC60F	ENCC60R
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$9D_H$	**CCU6_IENH** **Reset: 00_H** Capture/Compare Interrupt Enable Register High	Bit Field	ENSTR	ENIDLE	ENWHE	ENCHE	0	ENTRPF	ENT13PM	ENT13CM
		Type	rw	rw	rw	rw	r	rw	rw	rw
$9E_H$	**CCU6_INPL** **Reset: 40_H** Capture/Compare Interrupt Node Pointer Register Low	Bit Field	INPCHE		INPCC62		INPCC61		INPCC60	
		Type	rw		rw		rw		rw	
$9F_H$	**CCU6_INPH** **Reset: 39_H** Capture/Compare Interrupt Node Pointer Register High	Bit Field	0		INPT13		INPT12		INPERR	
		Type	r		rw		rw		rw	
$A4_H$	**CCU6_ISSL** **Reset: 00_H** Capture/Compare Interrupt Status Set Register Low	Bit Field	ST12PM	ST12OM	SCC62F	SCC62R	SCC61F	SCC61R	SCC60F	SCC60R
		Type	w	w	w	w	w	w	w	w
$A5_H$	**CCU6_ISSH** **Reset: 00_H** Capture/Compare Interrupt Status Set Register High	Bit Field	SSTR	SIDLE	SWHE	SCHE	SWHC	STRPF	ST13PM	ST13CM
		Type	w	w	w	w	w	w	w	w
$A6_H$	**CCU6_PSLR** **Reset: 00_H** Passive State Level Register	Bit Field	PSL63	0	PSL					
		Type	rwh	r	rwh					
$A7_H$	**CCU6_MCMCTR** **Reset: 00_H** Multi-Channel Mode Control Register	Bit Field	0		SWSYN		0	SWSEL		
		Type	r		rw		r	rw		
FA_H	**CCU6_TCTR2L** **Reset: 00_H** Timer Control Register 2 Low	Bit Field	0	T13TED	T13TEC				T13SSC	T12SSC
		Type	r	rw	rw				rw	rw

Table 14 CCU6 Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
FE_H	**CCU6_CMPSTATL Reset: 00_H** Compare State Register Low	Bit Field	0	CC63 ST	CC POS2	CC POS1	CC POS0	CC62 ST	CC61 ST	CC60 ST
		Type	r	rh	rh	rh	rh	rh	rh	rh
FF_H	**CCU6_CMPSTATH Reset: 00_H** Compare State Register High	Bit Field	T13IM	COUT 63PS	COUT 62PS	CC62 PS	COUT 61PS	CC61 PS	COUT 60PS	CC60 PS
		Type	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh

3.2.4.11 UART1 Registers

The UART1 SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 15 UART1 Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 1										
$C8_H$	**SCON Reset: 00_H** Serial Channel Control Register	Bit Field	SM0	SM1	SM2	REN	TB8	RB8	TI	RI
		Type	rw	rw	rw	rw	rw	rwh	rwh	rwh
$C9_H$	**SBUF Reset: 00_H** Serial Data Buffer Register	Bit Field	VAL							
		Type	rwh							
CA_H	**BCON Reset: 00_H** Baud Rate Control Register	Bit Field	0				BRPRE			R
		Type	r				rw			rw
CB_H	**BG Reset: 00_H** Baud Rate Timer/Reload Register	Bit Field	BR_VALUE							
		Type	rwh							
CC_H	**FDCON Reset: 00_H** Fractional Divider Control Register	Bit Field	0					NDOV	FDM	FDEN
		Type	r					rwh	rw	rw
CD_H	**FDSTEP Reset: 00_H** Fractional Divider Reload Register	Bit Field	STEP							
		Type	rw							
CE_H	**FDRES Reset: 00_H** Fractional Divider Result Register	Bit Field	RESULT							
		Type	rh							

3.2.4.12 SSC Registers

The SSC SFRs can be accessed in the standard memory area (RMAP = 0).

Table 16 SSC Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
$A9_H$	**SSC_PISEL** **Reset: 00_H** Port Input Select Register	Bit Field	0					CIS	SIS	MIS
		Type	r					rw	rw	rw
AA_H	**SSC_CONL** **Reset: 00_H** Control Register Low Programming Mode	Bit Field	LB	PO	PH	HB	BM			
		Type	rw	rw	rw	rw	rw			
AA_H	**SSC_CONL** **Reset: 00_H** Control Register Low Operating Mode	Bit Field	0				BC			
		Type	r				rh			
AB_H	**SSC_CONH** **Reset: 00_H** Control Register High Programming Mode	Bit Field	EN	MS	0	AREN	BEN	PEN	REN	TEN
		Type	rw	rw	r	rw	rw	rw	rw	rw
AB_H	**SSC_CONH** **Reset: 00_H** Control Register High Operating Mode	Bit Field	EN	MS	0	BSY	BE	PE	RE	TE
		Type	rw	rw	r	rh	rwh	rwh	rwh	rwh
AC_H	**SSC_TBL** **Reset: 00_H** Transmitter Buffer Register Low	Bit Field	TB_VALUE							
		Type	rw							
AD_H	**SSC_RBL** **Reset: 00_H** Receiver Buffer Register Low	Bit Field	RB_VALUE							
		Type	rh							
AE_H	**SSC_BRL** **Reset: 00_H** Baud Rate Timer Reload Register Low	Bit Field	BR_VALUE							
		Type	rw							
AF_H	**SSC_BRH** **Reset: 00_H** Baud Rate Timer Reload Register High	Bit Field	BR_VALUE							
		Type	rw							

3.2.4.13 MultiCAN Registers

The MultiCAN SFRs can be accessed in the standard memory area (RMAP = 0).

Table 17 CAN Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
$D8_H$	**ADCON** **Reset: 00_H** CAN Address/Data Control Register	Bit Field	V3	V2	V1	V0	AUAD		BSY	RWEN
		Type	rw	rw	rw	rw	rw		rh	rw
$D9_H$	**ADL** **Reset: 00_H** CAN Address Register Low	Bit Field	CA9	CA8	CA7	CA6	CA5	CA4	CA3	CA2
		Type	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh
DA_H	**ADH** **Reset: 00_H** CAN Address Register High	Bit Field	0				CA13	CA12	CA11	CA10
		Type	r				rwh	rwh	rwh	rwh

Table 18 OCDS Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
EC_H	**MMWR2** **Reset: 00_H** Monitor Work Register 2	Bit Field	MMWR2							
		Type	rw							

3.4.2 Interrupt Source and Vector

Each interrupt event source has an associated interrupt vector address for the interrupt node it belongs to. This vector is accessed to service the corresponding interrupt node request. The interrupt service of each interrupt source can be individually enabled or disabled via an enable bit. The assignment of the XC886/888 interrupt sources to the interrupt vector address and the corresponding interrupt node enable bits are summarized in **Table 20**.

Table 20 Interrupt Vector Addresses

Interrupt Source	Vector Address	Assignment for XC886/888	Enable Bit	SFR
NMI	0073_H	Watchdog Timer NMI	NMIWDT	NMICON
		PLL NMI	NMIPLL	
		Flash NMI	NMIFLASH	
		VDDC Prewarning NMI	NMIVDD	
		VDDP Prewarning NMI	NMIVDDP	
		Flash ECC NMI	NMIECC	
XINTR0	0003_H	External Interrupt 0	EX0	IEN0
XINTR1	$000B_H$	Timer 0	ET0	
XINTR2	0013_H	External Interrupt 1	EX1	
XINTR3	$001B_H$	Timer 1	ET1	
XINTR4	0023_H	UART	ES	
XINTR5	$002B_H$	T2	ET2	
		UART Fractional Divider (Normal Divider Overflow)		
		MultiCAN Node 0		
		LIN		

Figure 19 shows the structure of a bidirectional port pin.

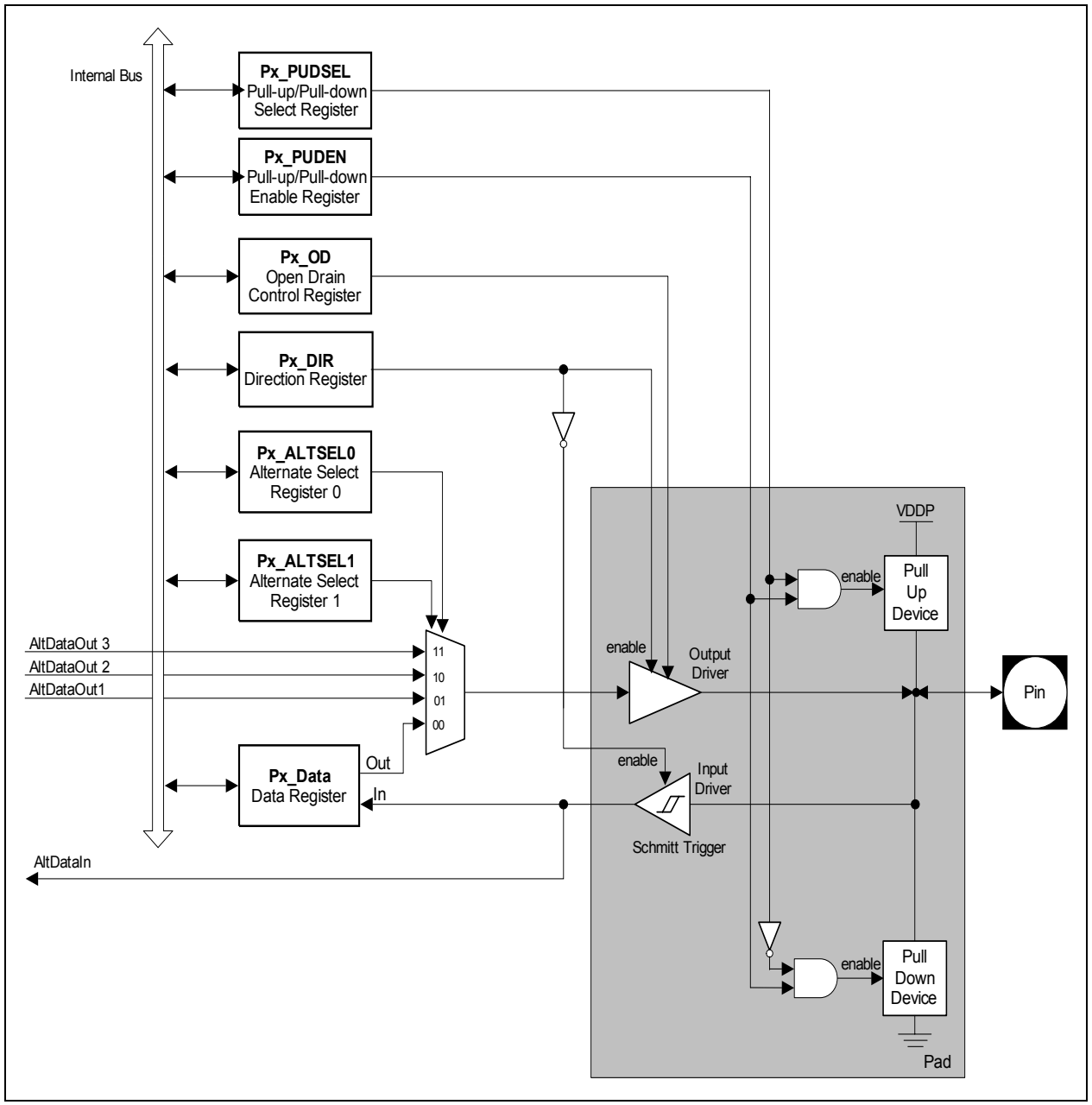


Figure 19 General Structure of Bidirectional Port

1) BSL mode is automatically entered if no valid password is installed and data at memory address 0000H equals zero.
2) OSC is bypassed in MultiCAN BSL mode
3) Normal user mode with standard JTAG (TCK,TDI,TDO) pins for hot-attach purpose.

Note: The boot options are valid only with the default set of UART and JTAG pins.

3.8 Clock Generation Unit

The Clock Generation Unit (CGU) allows great flexibility in the clock generation for the XC886/888. The power consumption is indirectly proportional to the frequency, whereas the performance of the microcontroller is directly proportional to the frequency. During user program execution, the frequency can be programmed for an optimal ratio between performance and power consumption. Therefore the power consumption can be adapted to the actual application state.

Features

- Phase-Locked Loop (PLL) for multiplying clock source by different factors
- PLL Base Mode
- Prescaler Mode
- PLL Mode
- Power-down mode support

The CGU consists of an oscillator circuit and a PLL. In the XC886/888, the oscillator can be from either of these two sources: the on-chip oscillator (9.6 MHz) or the external oscillator (4 MHz to 12 MHz). The term “oscillator” is used to refer to both on-chip oscillator and external oscillator, unless otherwise stated. After the reset, the on-chip oscillator will be used by default.The external oscillator can be selected via software. In addition, the PLL provides a fail-safe logic to perform oscillator run and loss-of-lock detection. This allows emergency routines to be executed for system recovery or to perform system shut down.

If the WDT is not serviced before the timer overflow, a system malfunction is assumed. As a result, the WDT NMI is triggered (assert FNMIWDT) and the reset prewarning is entered. The prewarning period lasts for 30_H count, after which the system is reset (assert WDTRST).

The WDT has a “programmable window boundary” which disallows any refresh during the WDT’s count-up. A refresh during this window boundary constitutes an invalid access to the WDT, causing the reset prewarning to be entered but without triggering the WDT NMI. The system will still be reset after the prewarning period is over. The window boundary is from 0000_H to the value obtained from the concatenation of WDTWINB and 00_H.

After being serviced, the WDT continues counting up from the value (<WDTREL> * 2^8). The time period for an overflow of the WDT is programmable in two ways:

- The input frequency to the WDT can be selected to be either $f_{PCLK}/2$ or $f_{PCLK}/128$
- The reload value WDTREL for the high byte of WDT can be programmed in register WDTREL

The period, P_{WDT}, between servicing the WDT and the next overflow can be determined by the following formula:

$$P_{WDT} = \frac{2^{(1 + WDTIN \times 6)} \times (2^{16} - WDTREL \times 2^8)}{f_{PCLK}} \quad (3.4)$$

If the Window-Boundary Refresh feature of the WDT is enabled, the period P_{WDT} between servicing the WDT and the next overflow is shortened if WDTWINB is greater than WDTREL, see **Figure 29**. This period can be calculated using the same formula by replacing WDTREL with WDTWINB. For this feature to be useful, WDTWINB cannot be smaller than WDTREL.

fractional divider) for generating a wide range of baud rates based on its input clock f_{PCLK}, see **Figure 30**.

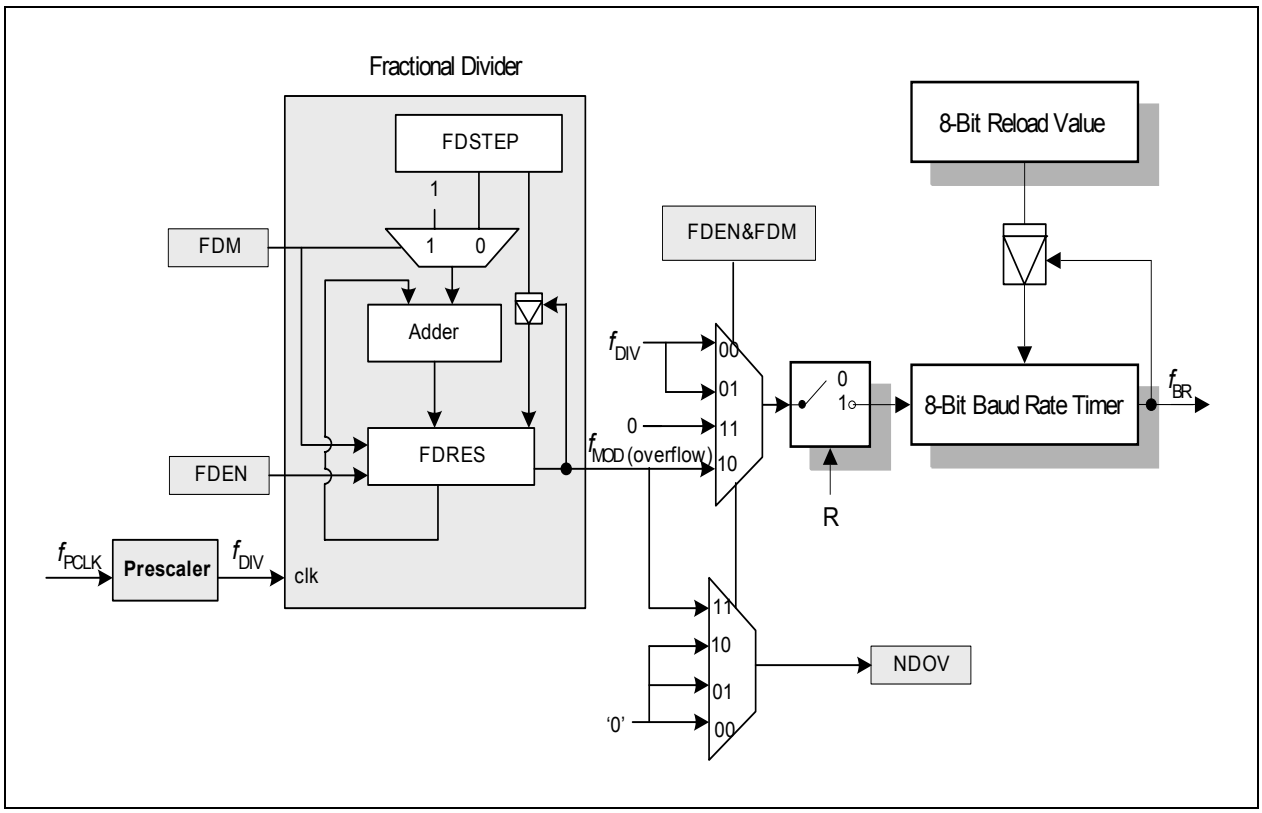


Figure 30 Baud-rate Generator Circuitry

The baud rate timer is a count-down timer and is clocked by either the output of the fractional divider (f_{MOD}) if the fractional divider is enabled (FDCON.FDEN = 1), or the output of the prescaler (f_{DIV}) if the fractional divider is disabled (FDEN = 0). For baud rate generation, the fractional divider must be configured to fractional divider mode (FDCON.FDM = 0). This allows the baud rate control run bit BCON.R to be used to start or stop the baud rate timer. At each timer underflow, the timer is reloaded with the 8-bit reload value in register BG and one clock pulse is generated for the serial channel.

Enabling the fractional divider in normal divider mode (FDEN = 1 and FDM = 1) stops the baud rate timer and nullifies the effect of bit BCON.R. See **Section 3.14**.

The baud rate (f_{BR}) value is dependent on the following parameters:

- Input clock f_{PCLK}
- Prescaling factor (2^{BRPRE}) defined by bit field BRPRE in register BCON
- Fractional divider (STEP/256) defined by register FDSTEP
  (to be considered only if fractional divider is enabled and operating in fractional divider mode)
- 8-bit reload value (BR_VALUE) for the baud rate timer defined by register BG

The following formulas calculate the final baud rate without and with the fractional divider respectively:

$$\text{baud rate} = \frac{f_{PCLK}}{16 \times 2^{BRPRE} \times (BR\_VALUE + 1)} \quad \text{where } 2^{BRPRE} \times (BR\_VALUE + 1) > 1 \tag{3.5}$$

$$\text{baud rate} = \frac{f_{PCLK}}{16 \times 2^{BRPRE} \times (BR\_VALUE + 1)} \times \frac{STEP}{256} \tag{3.6}$$

The maximum baud rate that can be generated is limited to $f_{PCLK}/32$. Hence, for a module clock of 24 MHz, the maximum achievable baud rate is 0.75 MBaud.

Standard LIN protocol can support a maximum baud rate of 20 kHz, the baud rate accuracy is not critical and the fractional divider can be disabled. Only the prescaler is used for auto baud rate calculation. For LIN fast mode, which supports the baud rate of 20 kHz to 115.2 kHz, the higher baud rates require the use of the fractional divider for greater accuracy.

Table 30 lists the various commonly used baud rates with their corresponding parameter settings and deviation errors. The fractional divider is disabled and a module clock of 24 MHz is used.

Table 30 Typical Baud rates for UART with Fractional Divider disabled

Baud rate	Prescaling Factor (2BRPRE)	Reload Value (BR_VALUE + 1)	Deviation Error
19.2 kBaud	1 (BRPRE=000_B)	78 ($4E_H$)	0.17 %
9600 Baud	1 (BRPRE=000_B)	156 ($9C_H$)	0.17 %
4800 Baud	2 (BRPRE=001_B)	156 ($9C_H$)	0.17 %
2400 Baud	4 (BRPRE=010_B)	156 ($9C_H$)	0.17 %

The fractional divider allows baud rates of higher accuracy (lower deviation error) to be generated. **Table 31** lists the resulting deviation errors from generating a baud rate of 115.2 kHz, using different module clock frequencies. The fractional divider is enabled (fractional divider mode) and the corresponding parameter settings are shown.

3.16 High-Speed Synchronous Serial Interface

The High-Speed Synchronous Serial Interface (SSC) supports full-duplex and half-duplex synchronous communication. The serial clock signal can be generated by the SSC internally (master mode), using its own 16-bit baud-rate generator, or can be received from an external master (slave mode). Data width, shift direction, clock polarity and phase are programmable. This allows communication with SPI-compatible devices or devices using other synchronous serial interfaces.

Features

- Master and slave mode operation
  - Full-duplex or half-duplex operation
- Transmit and receive buffered
- Flexible data format
  - Programmable number of data bits: 2 to 8 bits
  - Programmable shift direction: LSB or MSB shift first
  - Programmable clock polarity: idle low or high state for the shift clock
  - Programmable clock/data phase: data shift with leading or trailing edge of the shift clock
- Variable baud rate
- Compatible with Serial Peripheral Interface (SPI)
- Interrupt generation
  - On a transmitter empty condition
  - On a receiver full condition
  - On an error condition (receive, phase, baud rate, transmit error)

Data is transmitted or received on lines TXD and RXD, which are normally connected to the pins MTSR (Master Transmit/Slave Receive) and MRST (Master Receive/Slave Transmit). The clock signal is output via line MS_CLK (Master Serial Shift Clock) or input via line SS_CLK (Slave Serial Shift Clock). Both lines are normally connected to the pin SCLK. Transmission and reception of data are double-buffered.

Figure 32 shows the block diagram of the SSC.

3.20 Controller Area Network (MultiCAN)

The MultiCAN module contains two Full-CAN nodes operating independently or exchanging data and remote frames via a gateway function. Transmission and reception of CAN frames is handled in accordance to CAN specification V2.0 B active. Each CAN node can receive and transmit standard frames with 11-bit identifiers as well as extended frames with 29-bit identifiers.

Both CAN nodes share a common set of message objects, where each message object may be individually allocated to one of the CAN nodes. Besides serving as a storage container for incoming and outgoing frames, message objects may be combined to build gateways between the CAN nodes or to setup a FIFO buffer.

The message objects are organized in double chained lists, where each CAN node has it's own list of message objects. A CAN node stores frames only into message objects that are allocated to the list of the CAN node. It only transmits messages from objects of this list. A powerful, command driven list controller performs all list operations.

The bit timings for the CAN nodes are derived from the peripheral clock (f_{CAN}) and are programmable up to a data rate of 1 MBaud. A pair of receive and transmit pins connects each CAN node to a bus transceiver.

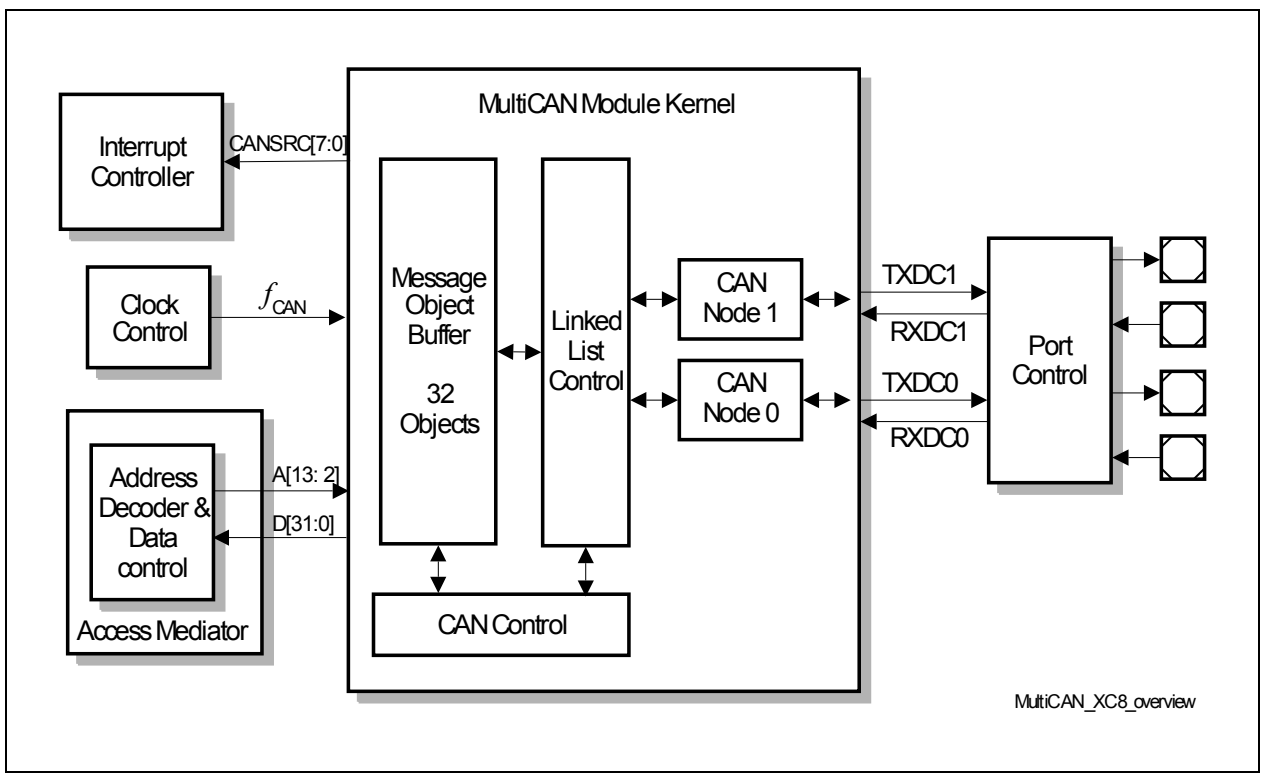


Figure 34 Overview of the MultiCAN

Features

- Compliant to ISO 11898.

4.2.2 Supply Threshold Characteristics

Table 39 provides the characteristics of the supply threshold in the XC886/888.

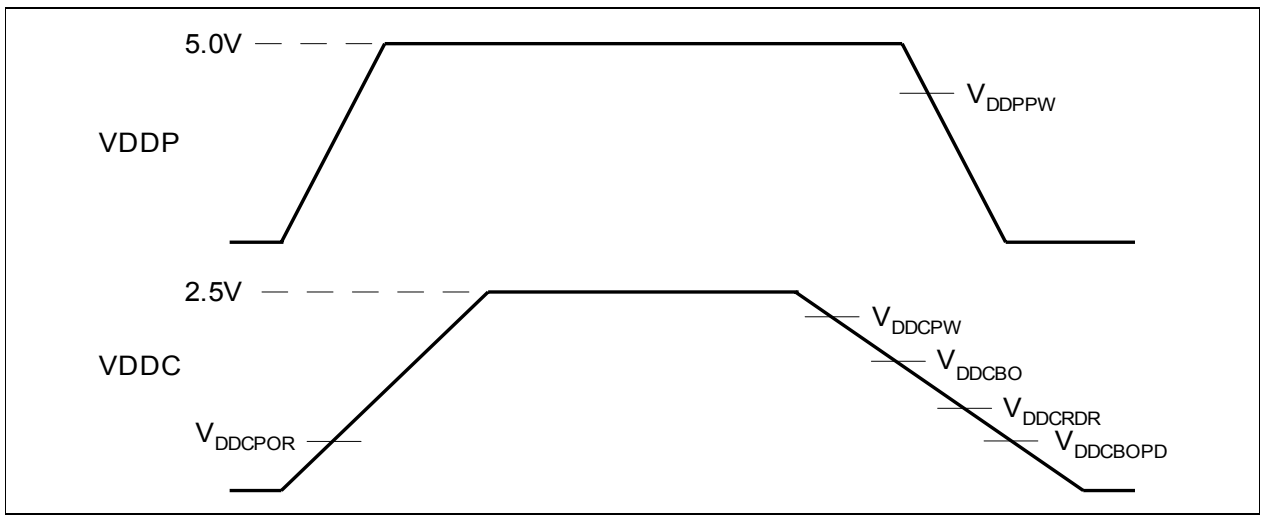


Figure 38 Supply Threshold Parameters

Table 39 Supply Threshold Parameters (Operating Conditions apply)

Parameters	Symbol		Limit Values			Unit
			min.	typ.	max.	
V_{DDC} prewarning voltage[1)]	V_{DDCPW}	CC	2.2	2.3	2.4	V
V_{DDC} brownout voltage in active mode[1)]	V_{DDCBO}	CC	2.0	2.1	2.2	V
RAM data retention voltage	V_{DDCRDR}	CC	0.9	1.0	1.1	V
V_{DDC} brownout voltage in power-down mode[2)]	$V_{DDCBOPD}$	CC	1.3	1.5	1.7	V
V_{DDP} prewarning voltage[3)]	V_{DDPPW}	CC	3.4	4.0	4.6	V
Power-on reset voltage[2)4)]	V_{DDCPOR}	CC	1.3	1.5	1.7	V

1) Detection is disabled in power-down mode.

2) Detection is enabled in both active and power-down mode.

3) Detection is enabled for external power supply of 5.0V.
Detection must be disabled for external power supply of 3.3V.

4) The reset of EVR is extended by 300 µs typically after the VDDC reaches the power-on reset voltage.

Table 42 Power Down Current (Operating Conditions apply; V_{DDP} = 5V range)

Parameter	Symbol	Limit Values		Unit	Test Condition
		typ.[1]	max.[2]		
V_{DDP} = 5V Range					
Power-Down Mode	I_{PDP}	1	10	µA	T_A = + 25 °C[3][4]
		-	30	µA	T_A = + 85 °C[4][5]

1) The typical I_{PDP} values are measured at V_{DDP} = 5.0 V.

2) The maximum I_{PDP} values are measured at V_{DDP} = 5.5 V.

3) I_{PDP} has a maximum value of 200 µA at T_A = + 125 °C.

4) I_{PDP} is measured with: $\overline{\text{RESET}}$ = V_{DDP}, V_{AGND}= V_{SS}, RXD/INT0 = V_{DDP}; rest of the ports are programmed to be input with either internal pull devices enabled or driven externally to ensure no floating inputs.

5) Not subjected to production test, verified by design/characterization.

4.3 AC Parameters

The electrical characteristics of the AC Parameters are detailed in this section.

4.3.1 Testing Waveforms

The testing waveforms for rise/fall time, output delay and output high impedance are shown in **Figure 40**, **Figure 41** and **Figure 42**.

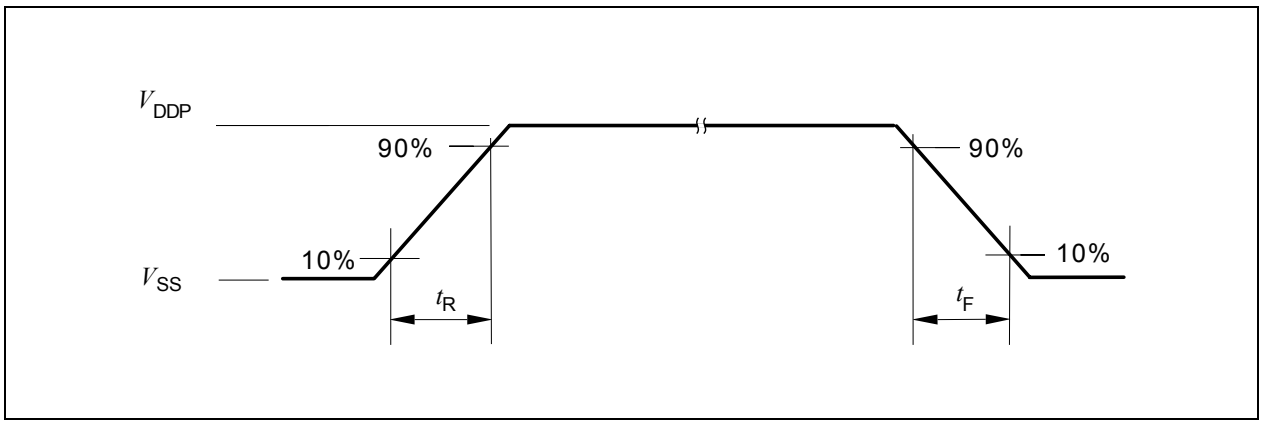


Figure 40 Rise/Fall Time Parameters

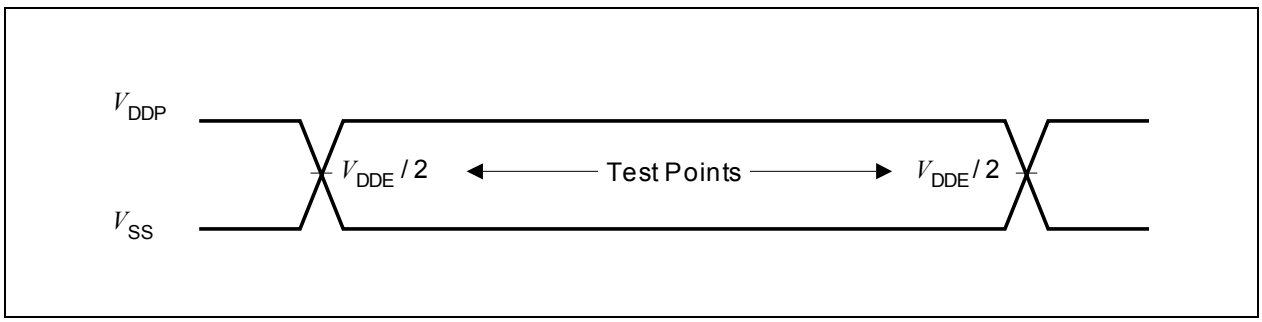


Figure 41 Testing Waveform, Output Delay

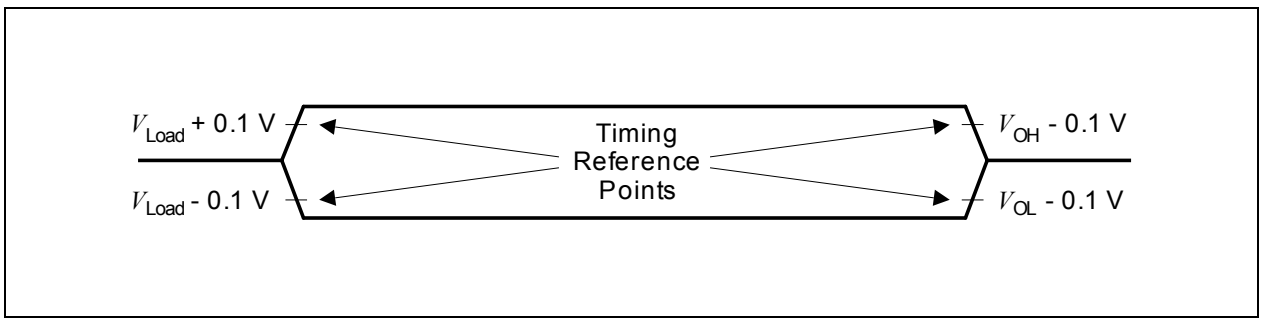


Figure 42 Testing Waveform, Output High Impedance

4.3.3 Power-on Reset and PLL Timing

Table 49 provides the characteristics of the power-on reset and PLL timing in the XC886/888.

Table 46 Power-On Reset and PLL Timing (Operating Conditions apply)

Parameter	Symbol		Limit Values			Unit	Test Conditions
			min.	typ.	max.		
Pad operating voltage	V_{PAD}	CC	2.3	–	–	V	1)
On-Chip Oscillator start-up time	t_{OSCST}	CC	–	–	500	ns	1)
Flash initialization time	t_{FINIT}	CC	–	160	–	µs	1)
$\overline{\text{RESET}}$ hold time	t_{RST}	SR	–	500	–	µs	V_{DDP} rise time (10% – 90%) ≤ 500µs 1)2)
PLL lock-in in time	t_{LOCK}	CC	–	–	200	µs	1)
PLL accumulated jitter	D_P		–	–	0.7	ns	1)3)

1) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

2) $\overline{\text{RESET}}$ signal has to be active (low) until V_{DDC} has reached 90% of its maximum value (typ. 2.5 V).

3) PLL lock at 96 MHz using a 4 MHz external oscillator. The PLL Divider settings are K = 2, N = 48 and P = 1.

4.3.7 SSC Master Mode Timing

Table 51 provides the characteristics of the SSC timing in the XC886/888.

Table 51 SSC Master Mode Timing (Operating Conditions apply; CL = 50 pF)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			min.	max.		
SCLK clock period	t_0	CC	$2*T_{SSC}$	–	ns	1)2)
MTSR delay from SCLK ↓	t_1	CC	0	8	ns	2)
MRST setup to SCLK ↓	t_2	SR	24	–	ns	2)
MRST hold from SCLK ↓	t_3	SR	0	–	ns	2)

1) $T_{SSCmin} = T_{CPU} = 1/f_{CPU}$. When f_{CPU} = 24 MHz, t_0 = 83.3ns. T_{CPU} is the CPU clock period.

2) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

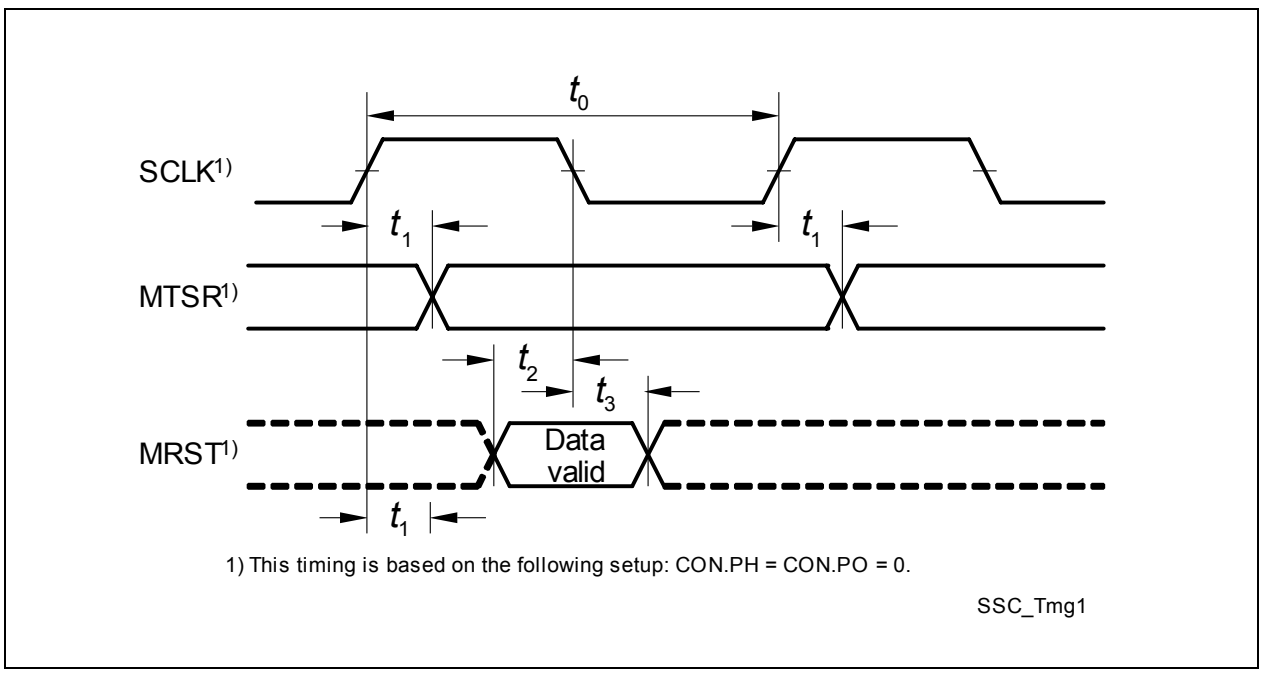
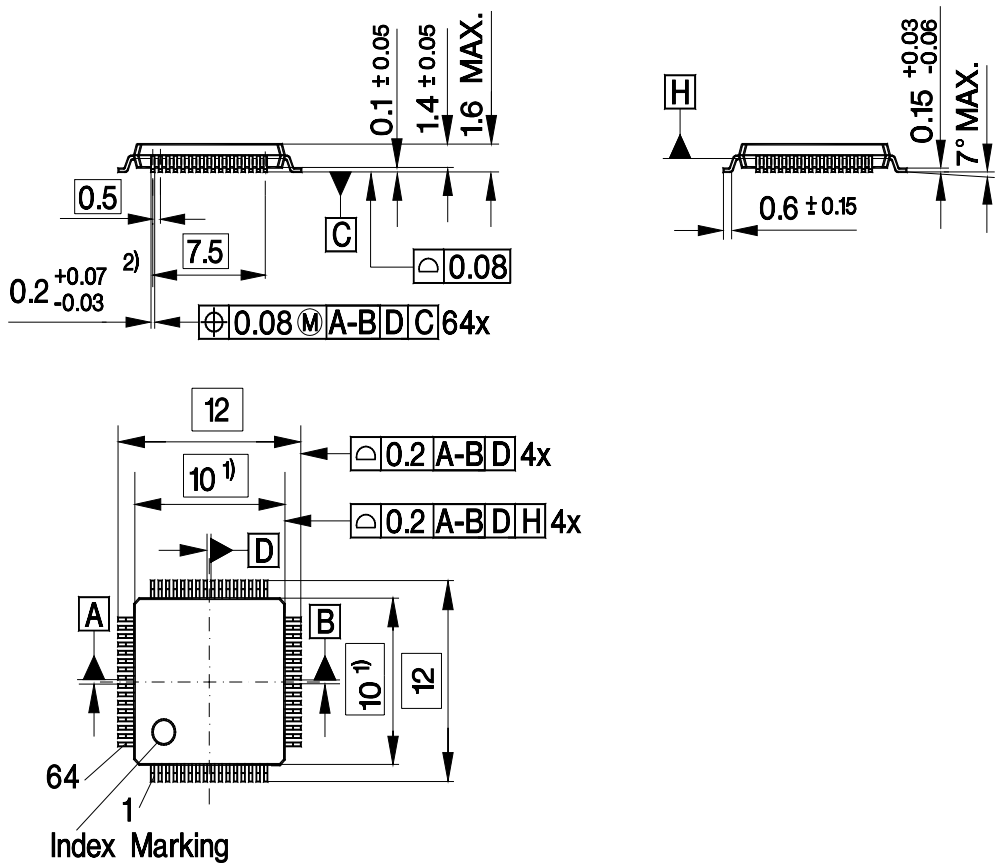


Figure 52 SSC Master Mode Timing

Figure 49 shows the package outlines of the XC888.



1) Does not include plastic or metal protrusion of 0.25 max. per side
2) Does not include dambar protrusion of 0.08 max. per side

Figure 49 PG-TQFP-64 Package Outline

5.3 Quality Declaration

Table 2 shows the characteristics of the quality parameters in the XC886/888.

Table 2 Quality Parameters

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
ESD susceptibility according to Human Body Model (HBM)	V_{HBM}	-	2000	V	Conforming to EIA/JESD22-A114-B[1)]
ESD susceptibility according to Charged Device Model (CDM) pins	V_{CDM}	-	500	V	Conforming to JESD22-C101-C[1)]

1) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.